

SEMICONDUCTOR PACKAGES FOR SEMICONDUCTOR DEVICES

ABSTRACT OF THE DISCLOSURE

A semiconductor die package is disclosed. In one embodiment, the die package includes a semiconductor die having a vertical power transistor, a first surface and a second surface. A ground plane proximate the second surface and distal to the first surface. A bus member covers a portion the first surface of the semiconductor die and has at least one leg that electrically couples a source region of the semiconductor die to the ground plane.

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